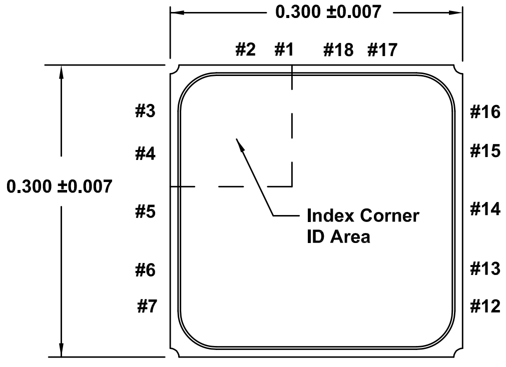
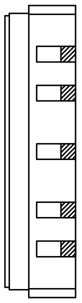
## Package Outline Drawing

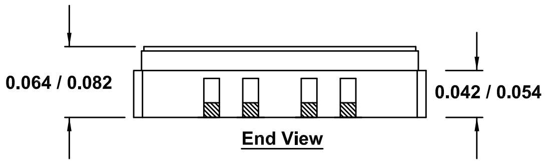
J18.C
18 Pad Ceramic Leadless Chip Carrier (CLCC)
Rev 0, 11/2022



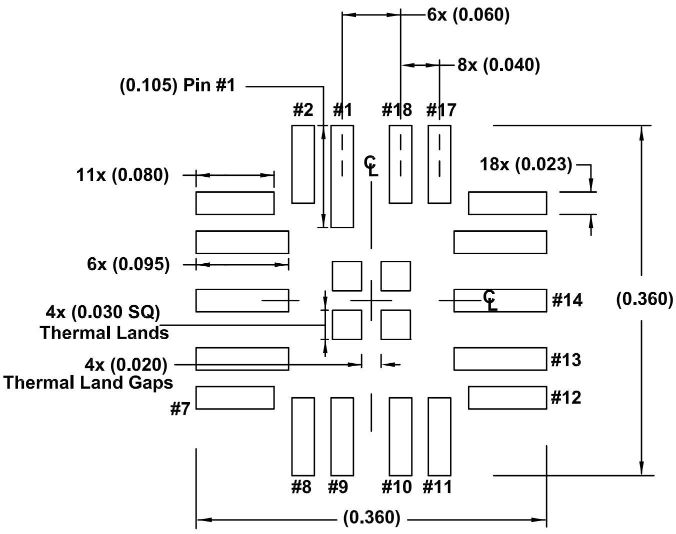
Top View



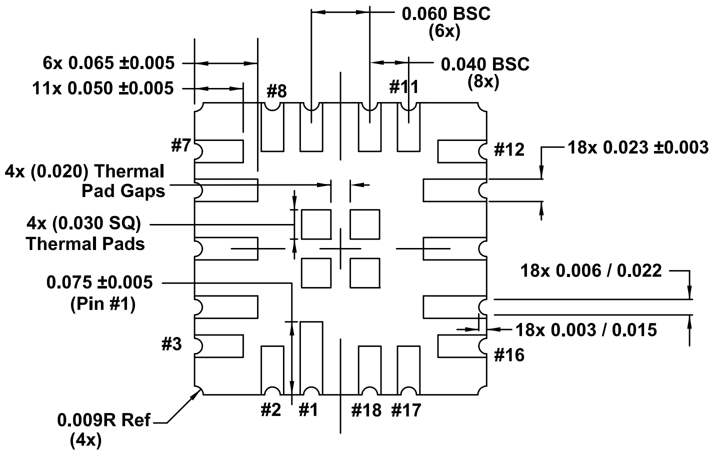
Side View



End View



Recommended Land Pattern



Bottom View

**Notes:**

1. The corner shape (such as radius, or chamfer) may vary at the manufacturers option from that shown on the drawing.
2. The package thickness dimension is the package height before being solder dipped.
3. Dimensions are in inches.